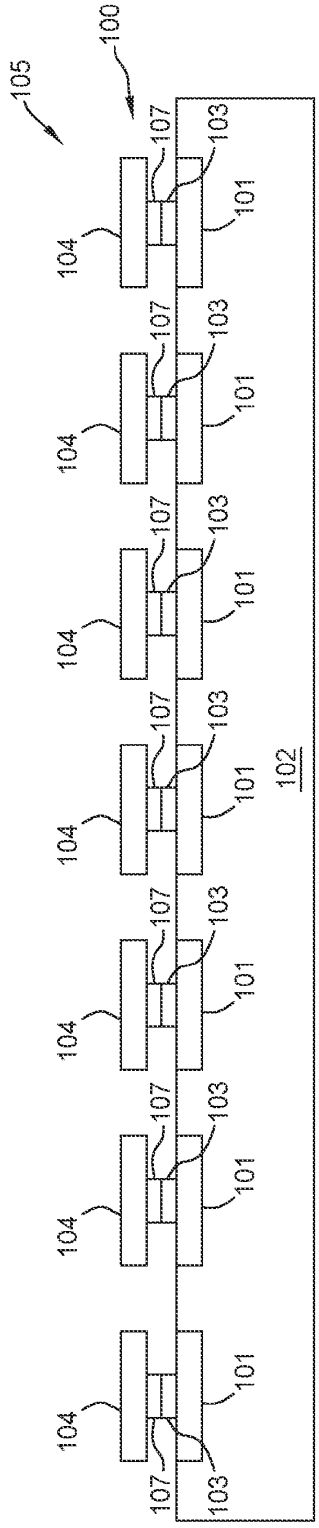


FIG. 1A

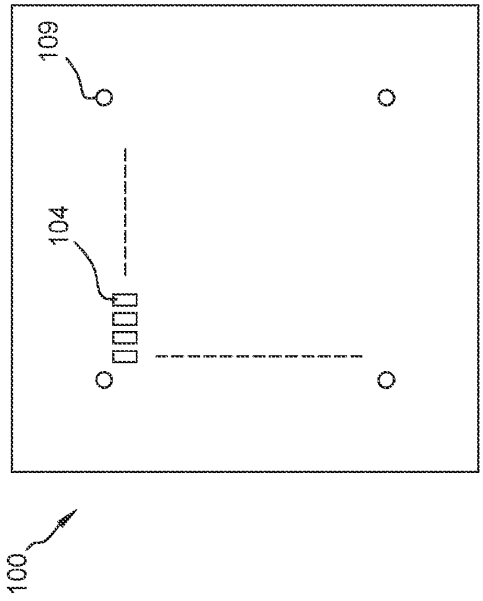


FIG. 1B

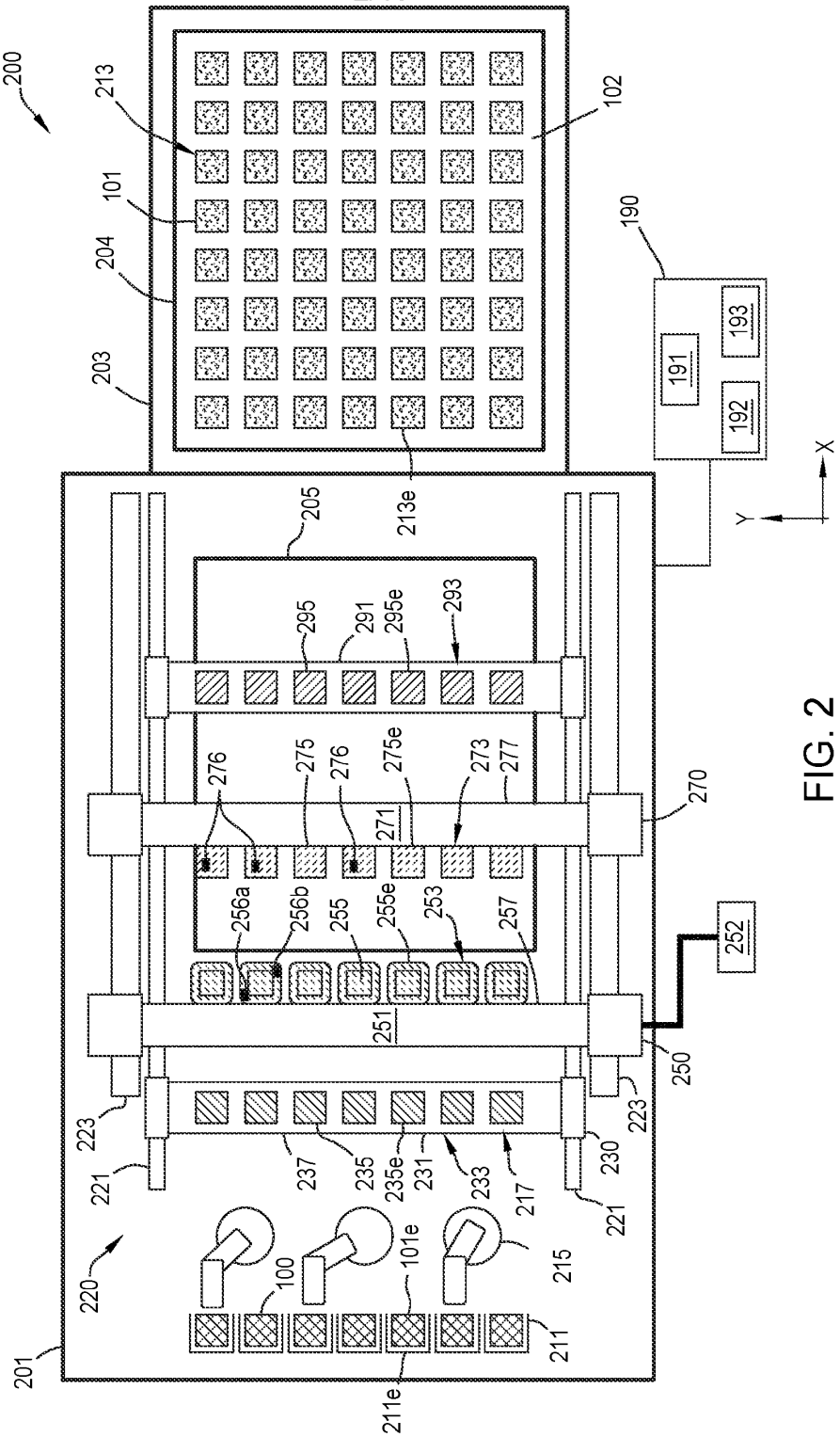

200
213
102
101
204
203
190
191
193
192
X
Y
205
213e
295
291
295e
293
276
275
276
275e
273
277
270
271
256a
256b
255
255e
253
257
252
251
250
223
221
237
235
235e
231
233
217
230
220
100
101e
215
211
201
211e

FIG. 2

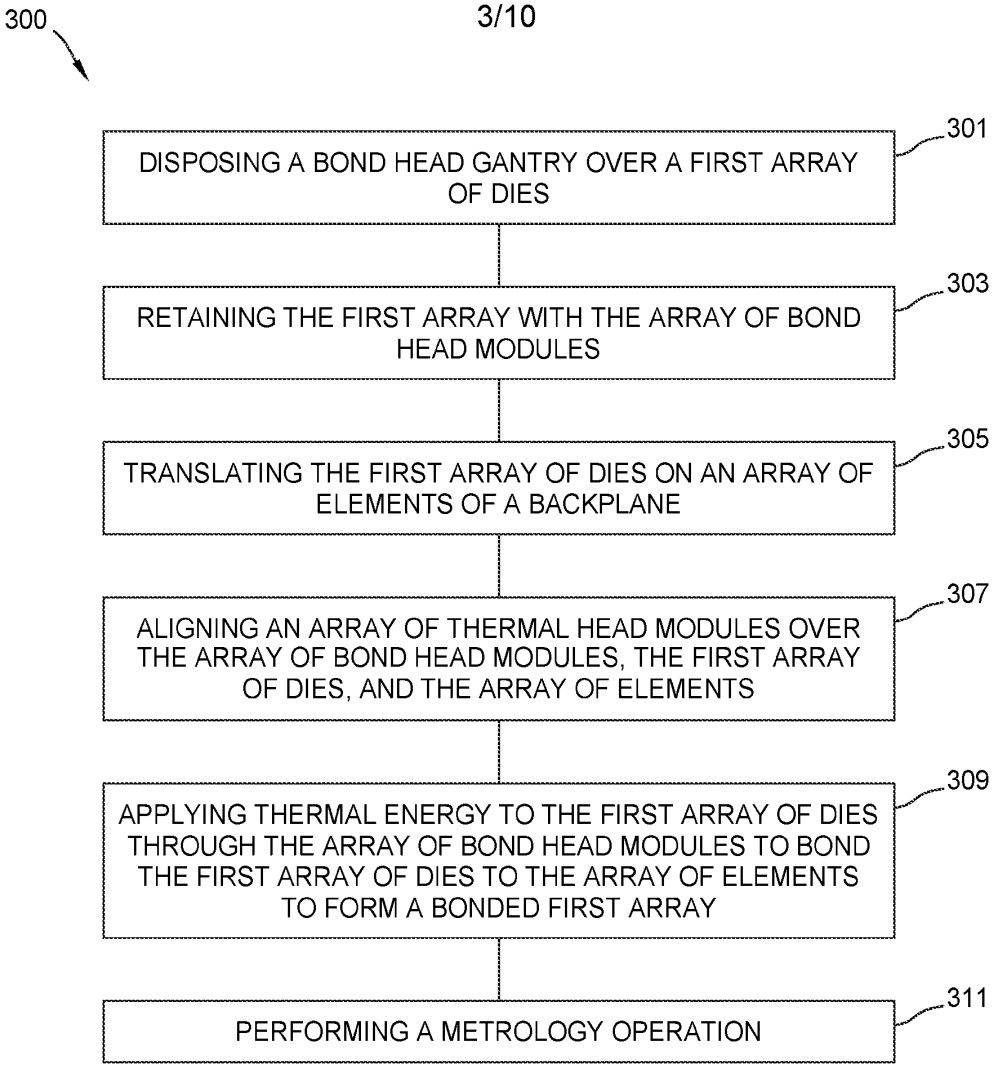

300
DISPOSING A BOND HEAD GANTRY OVER A FIRST ARRAY OF DIES
301
RETAINING THE FIRST ARRAY WITH THE ARRAY OF BOND HEAD MODULES
303
TRANSLATING THE FIRST ARRAY OF DIES ON AN ARRAY OF ELEMENTS OF A BACKPLANE
305
ALIGNING AN ARRAY OF THERMAL HEAD MODULES OVER THE ARRAY OF BOND HEAD MODULES, THE FIRST ARRAY OF DIES, AND THE ARRAY OF ELEMENTS
307
APPLYING THERMAL ENERGY TO THE FIRST ARRAY OF DIES THROUGH THE ARRAY OF BOND HEAD MODULES TO BOND THE FIRST ARRAY OF DIES TO THE ARRAY OF ELEMENTS TO FORM A BONDED FIRST ARRAY
309
PERFORMING A METROLOGY OPERATION
311

FIG. 3

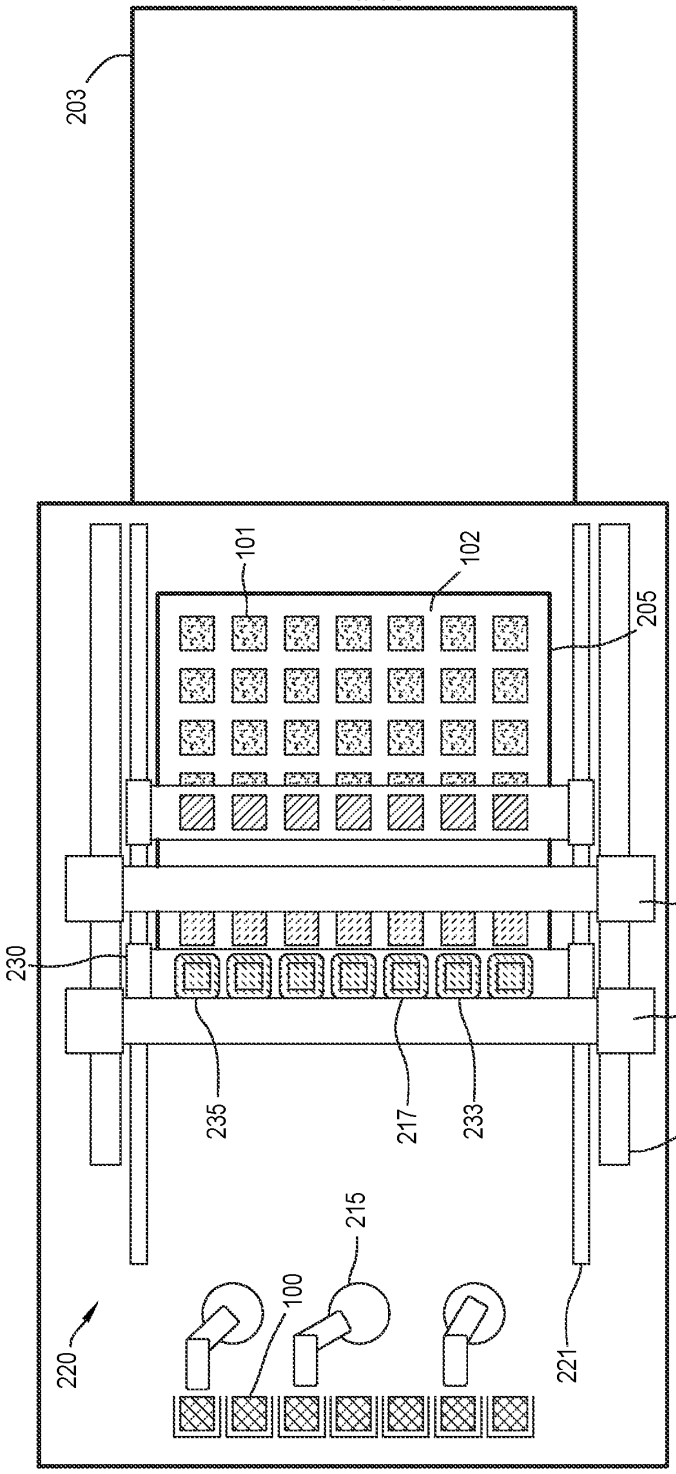


FIG. 4

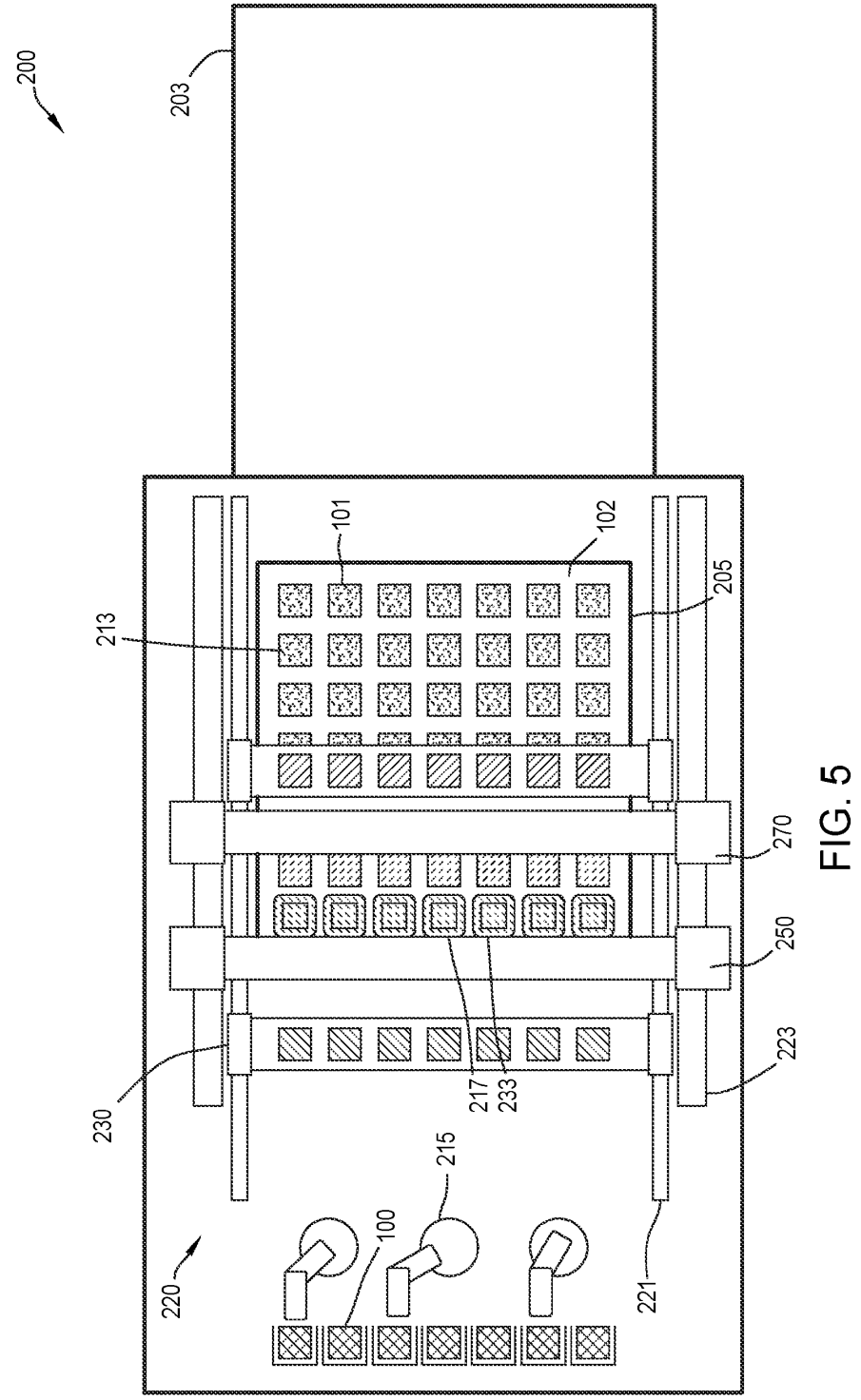


FIG. 5

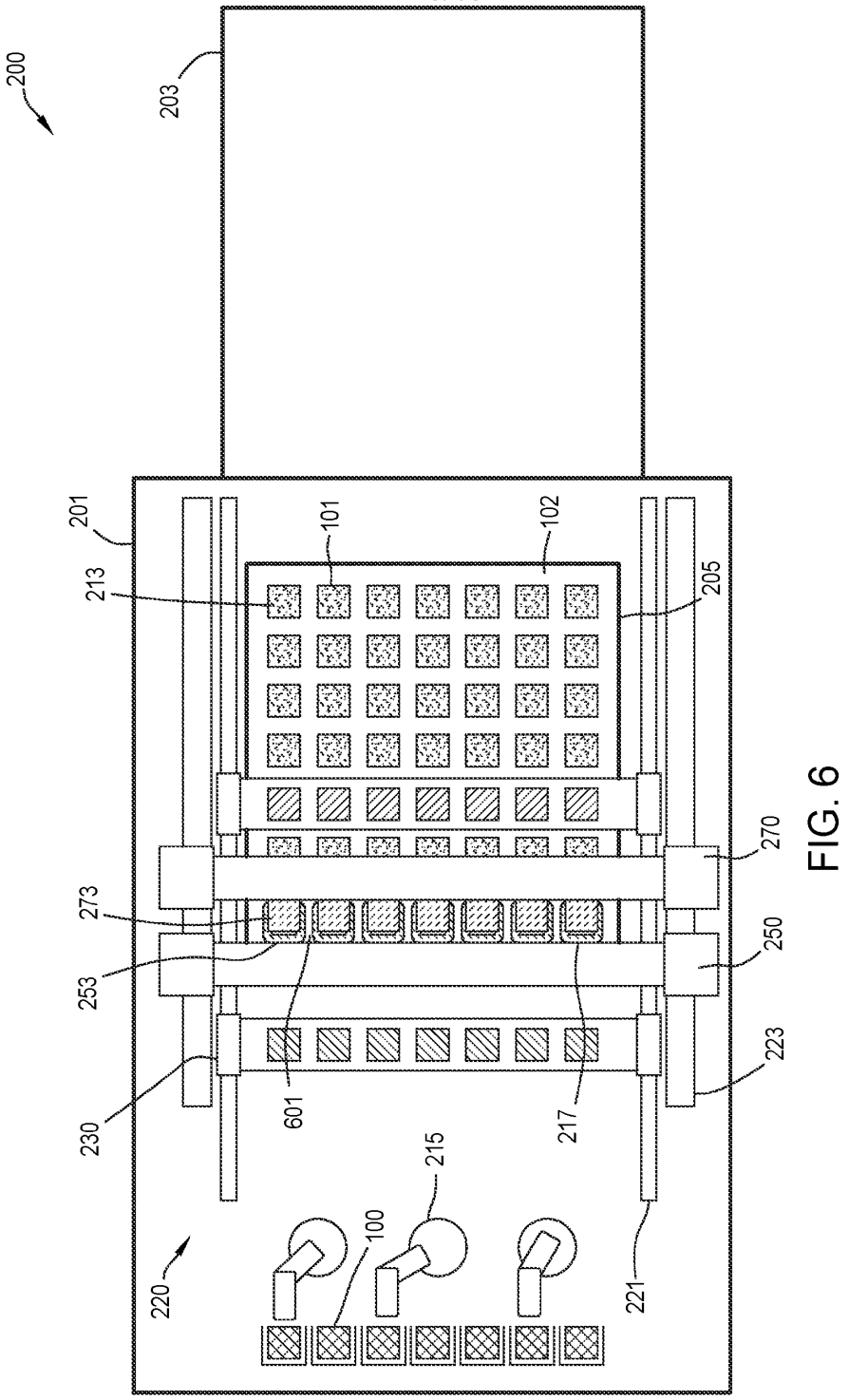

200
203
201
101
102
213
205
270
273
250
253
223
230
601
217
215
100
220
221

FIG. 6

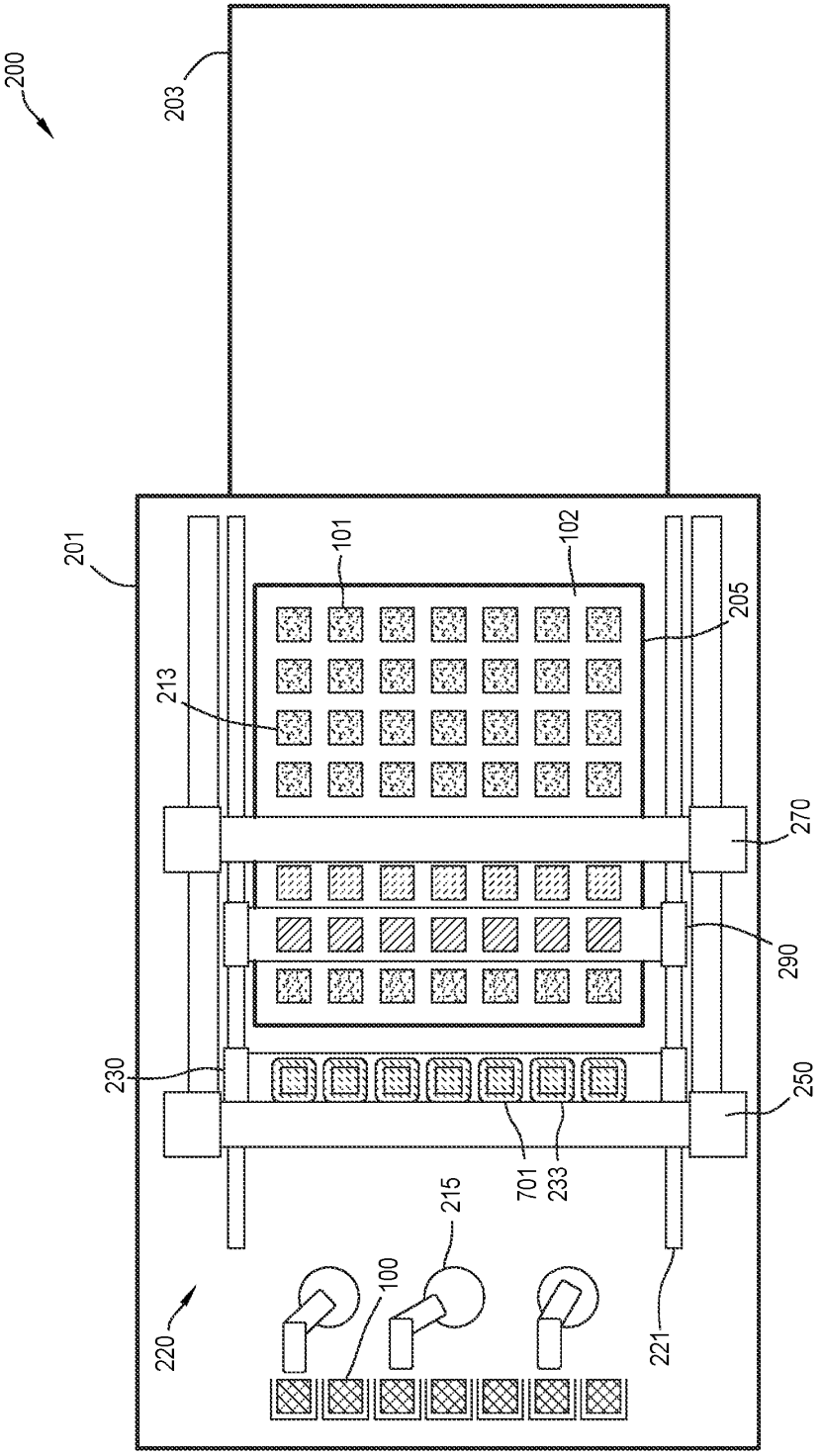

200
203
201
101
102
205
213
270
290
230
250
701
233
215
100
220
221

FIG. 7

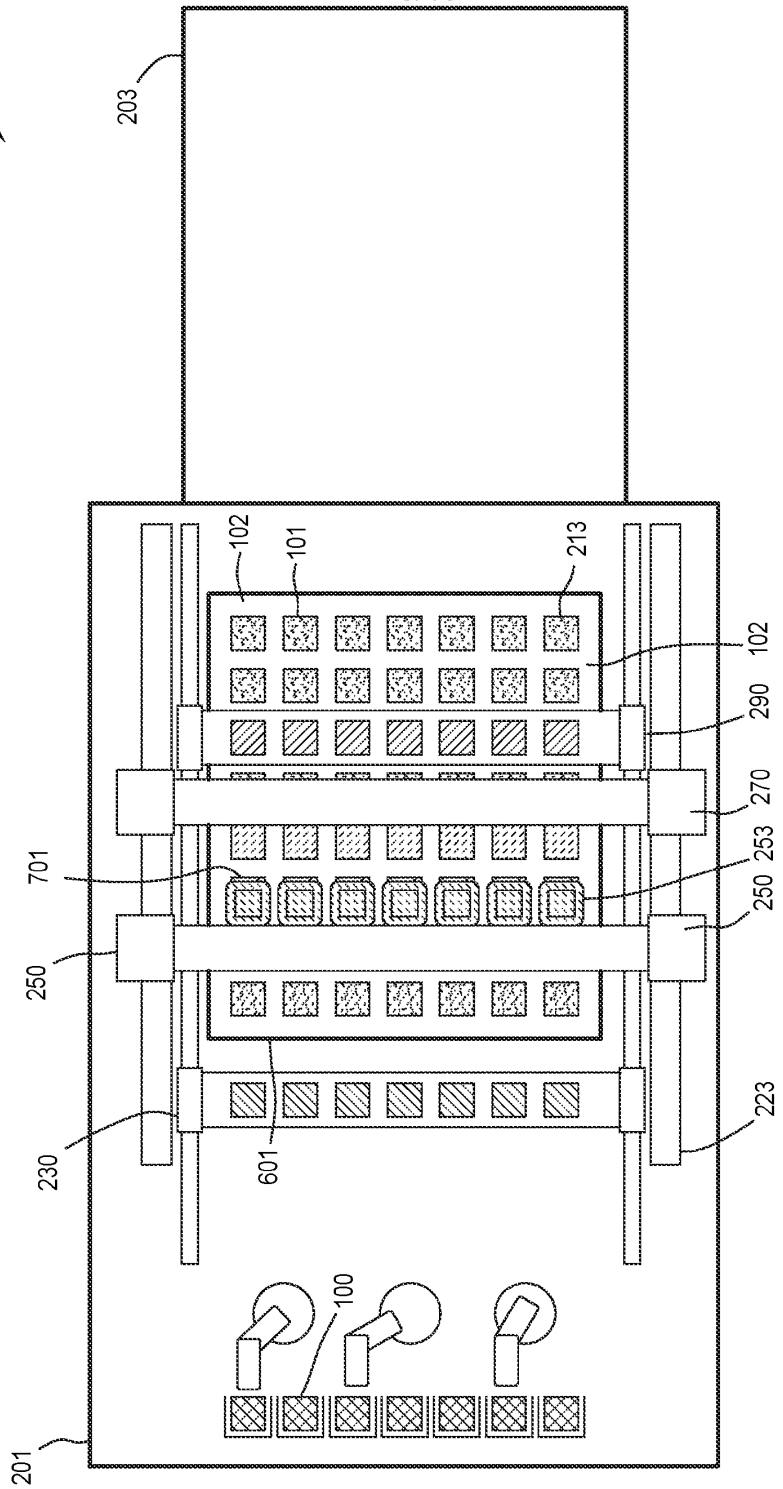

200
203
102
101
213
102
290
270
253
250
701
250
230
601
223
100
201

FIG. 8

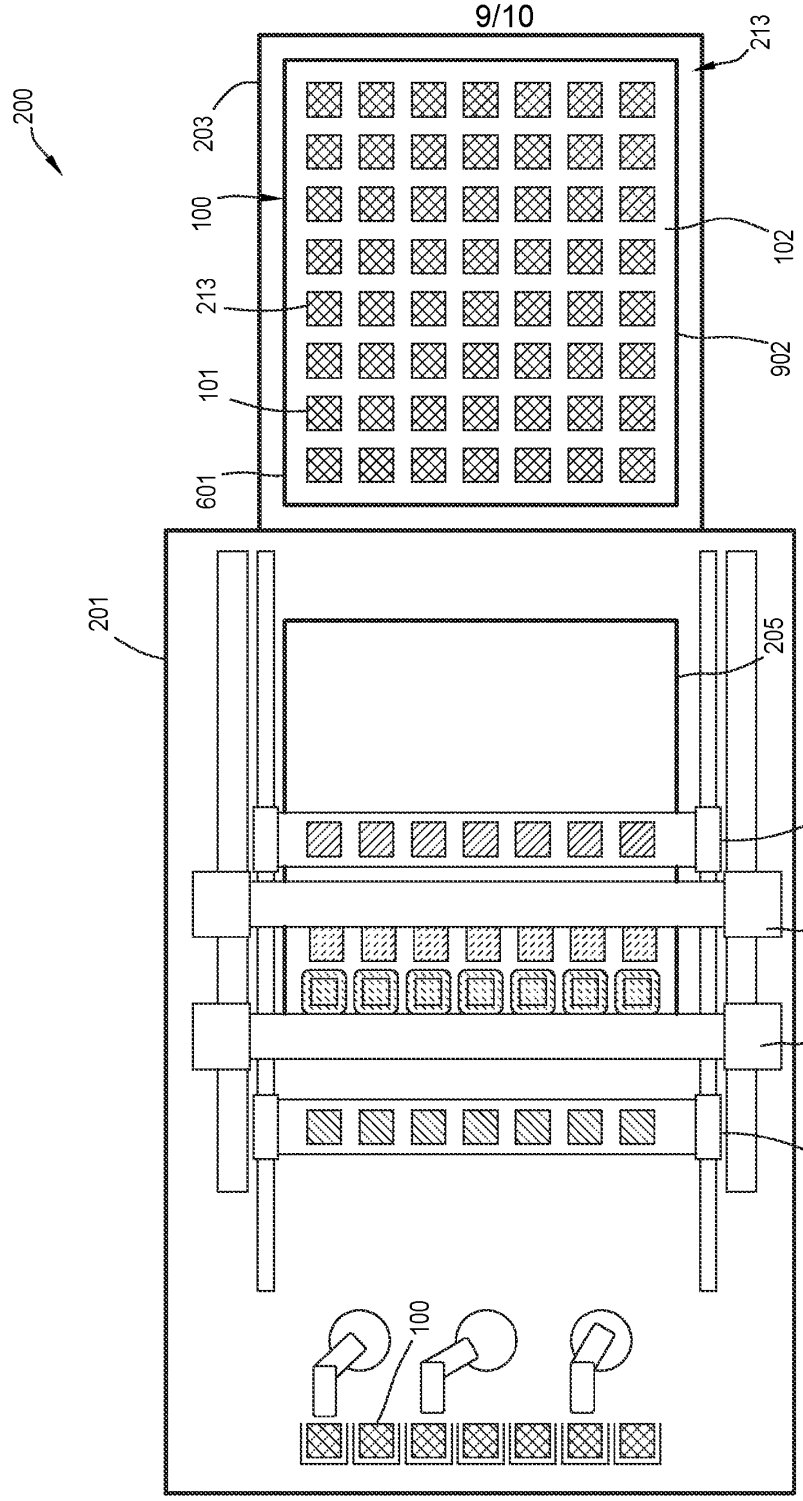


FIG. 9

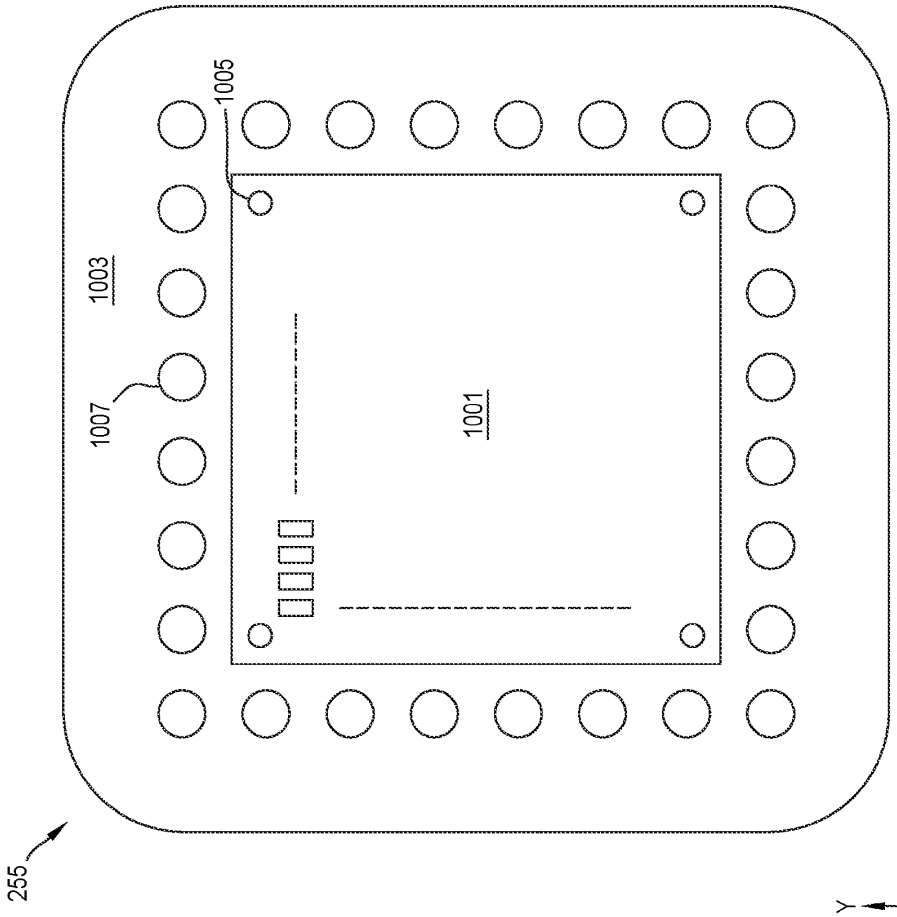


FIG. 10